

IN THE SPECIFICATION

Amend the paragraph beginning at page 20, line 1 as follows.

Moreover, the first semiconductor chip 1, the adhesive layer 3, the second semiconductor chip 2, insulator 4, and the first and second conductive wires 5 and 6 are sealed with sealing material, such as an epoxy molding compound. The area sealed with the sealing material is defined as a sealing part 8. A portion 8a of the sealing part 8 is between the input-output pads 1c of the second surface 1b of the first semiconductor chip 1 and the insulator 4 outward of the adhesive layer 3.